

Medical Device Packaging UW-Stout Course



**ASTM COMMITTEE F02 ON FLEXIBLE
BARRIER PACKAGING**

Background



- Development started 2012
- Focus on industry involvement
- First taught, fall 2013
- Participants
 - Dan Burgess, Boston Scientific
 - Bill Daeschler, Oliver-Tolas
 - Aaron Guggemos, Boston Scientific
 - Don Handrow, Prent
 - Stacy, Kromenhoek, Boston Scientific
 - Curt Larsen, Consultant
 - Mark Ralph, Medtronic
 - Jane Severin, DuPont
 - Richard Tuma, Boston Scientific
 - Kevin Zacharias, Oliver-Tolas

Overview



- Course initially being taught by industry
- Students learn about medical device development process beginning to end
- Presentations include; mock design reviews and final presentation

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